

0057-2608-2YY

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

Toshiaki SHINOHARA, et al.

: EXAMINER: CHU, Chris C.

SERIAL NO: 09/534,043

FILED: March 24, 2000

: GROUP ART UNIT: 2815

FOR: SEMICONDUCTOR MODULE  
AND INSULATING SUBSTRATE  
THEREFOR

#11/C  
12/17/02  
John H.  
Entered  
in  
2/13/03

AMENDMENT AFTER FINAL OFFICE ACTION

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

In response to the Official Action dated September 11, 2002, please amend the above-identified application as follows:

IN THE CLAIMS

Please amend Claim 1 as shown below in clean form. A marked-up copy of the amended claim is attached hereto.

1. (Twice Amended) A semiconductor module mountable on an external heat sink,  
said semiconductor module comprising:

an insulating substrate for said semiconductor module, said insulating substrate including a substrate, a first conductive pattern formed on a first main surface of said substrate which is on the opposite side from said external heat sink, and a second conductive pattern formed on a second main surface of said substrate which is on the same side as said external heat sink and for contact with said external heat sink; and

Sub  
E1

C1